

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- Low On-Resistance
- Fast Switching Speed
- Drive Circuits can be Simple
- Parallel Use is Easy
- Low Voltage Drive Makes This Device Ideal for Portable Equipment
- Reliable and Rugged
- Green Device Available
- ESD Protection

APPLICATION

- Interfacing
- Switching

MARKING

39K

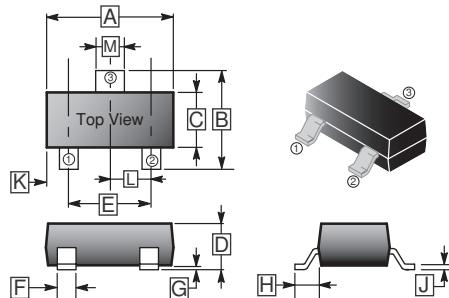
PACKAGE INFORMATION

Package	MPQ	Leader Size
SOT-523	3K	7 inch

ORDER INFORMATION

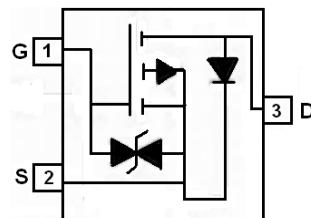
Part Number	Type
SCG3139K-C	Lead (Pb)-free and Halogen-free

SOT-523



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	1.5	1.7	G	-	0.1
B	1.45	1.75	H	0.55	REF.
C	0.7	0.9	J	0.1	0.2
D	0.7	0.9	K	-	-
E	0.9	1.1	L	0.5 TYP.	
F	0.15	0.35	M	0.25	0.35

Top View



MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ¹ $V_{GS} @ -4.5\text{V}$	I_D	-0.5	A
		-0.4	
Pulsed Drain Current ³	I_{DM}	-1.5	A
Total Power Dissipation	P_D	280	mW
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55~150	°C
Thermal Resistance Ratings			
Thermal Resistance Junction-ambient ¹	$R_{\theta JA}$	450	°C/W
Thermal Resistance Junction-ambient ²		735	

ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ unless otherwise specified)

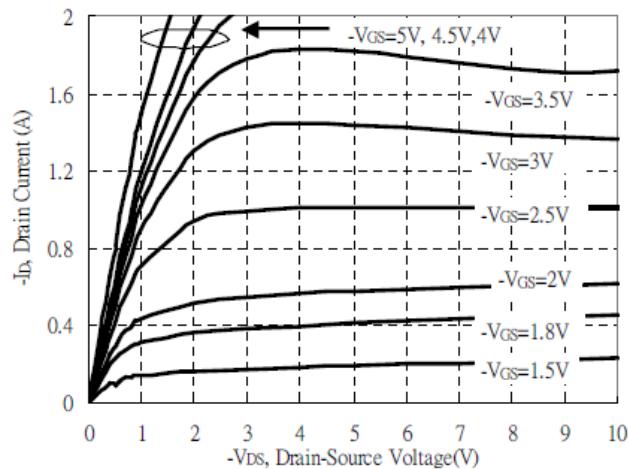
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	-20	-	-	V	$\text{V}_{\text{GS}}=0, \text{I}_D= -250\mu\text{A}$
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	-0.5	-	-1.2	V	$\text{V}_{\text{DS}}= \text{V}_{\text{GS}}, \text{I}_D= -250\mu\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 10	μA	$\text{V}_{\text{GS}}= \pm 8\text{V}$
Drain-Source Leakage Current	$\text{T}_J=25^\circ\text{C}$	I_{DSS}	-	-	μA	$\text{V}_{\text{DS}}= -20\text{V}, \text{V}_{\text{GS}}=0$
	$\text{T}_J=55^\circ\text{C}$	I_{DSS}	-	-	μA	
Static Drain-Source On-Resistance ⁴	$\text{R}_{\text{DS(ON)}}$	-	-	0.9	Ω	$\text{V}_{\text{GS}}= -4.5\text{V}, \text{I}_D= -500\text{mA}$
		-	-	1.4		$\text{V}_{\text{GS}}= -2.5\text{V}, \text{I}_D= -300\text{mA}$
		-	-	2.7		$\text{V}_{\text{GS}}= -1.8\text{V}, \text{I}_D= -150\text{mA}$
Total Gate Charge	Q_g	-	1.5	-	nC	$\text{I}_{\text{DS}}= -0.25\text{A}$ $\text{V}_{\text{DS}}= -10\text{V}$ $\text{V}_{\text{GS}}= -4.5\text{V}$
Gate-Source Charge	Q_{gs}	-	0.28	-		
Gate-Drain ("Miller") Charge	Q_{gd}	-	0.44	-		
Turn-on Delay Time	$\text{T}_{\text{d(on)}}$	-	30.6	-	nS	$\text{V}_{\text{DD}}= -10\text{V}$ $\text{I}_{\text{DS}}= -0.2\text{A}$ $\text{V}_{\text{GS}}= -4.5\text{V}$ $\text{R}_{\text{GEN}}=10\Omega$
Rise Time	T_r	-	48.4	-		
Turn-off Delay Time	$\text{T}_{\text{d(off)}}$	-	13.5	-		
Fall Time	T_f	-	14.4	-		
Input Capacitance	C_{iss}	-	46	-	pF	$\text{V}_{\text{DS}}= -10\text{V}$ $\text{V}_{\text{GS}}=0$ $f=1\text{MHz}$
Output Capacitance	C_{oss}	-	27	-		
Reverse Transfer Capacitance	C_{rss}	-	17	-		
Source-Drain Diode						
Continuous Source Current ¹	I_s	-	-	-0.5	A	
Pulsed Source Current ³	I_{SM}	-	-	-1.5		
Diode Forward Voltage ⁴	V_{SD}	-	-	-1.2		V $\text{I}_s= -150\text{mA}, \text{V}_{\text{GS}}=0$

Notes:

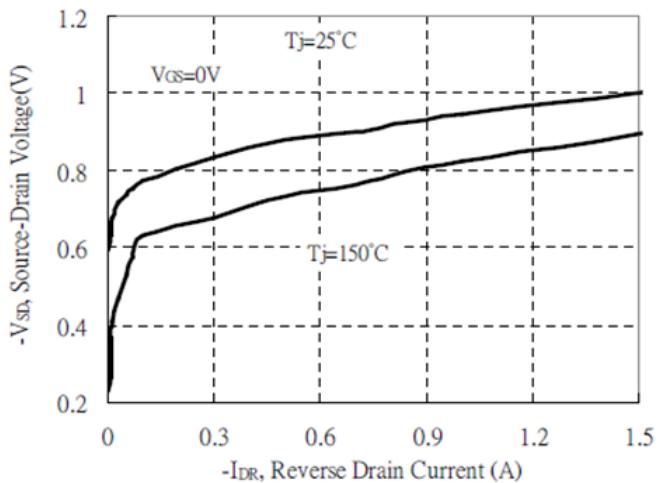
1. Surface mounted on a 1 inch² FR-4 board with 2OZ copper, $t \leq 5$ sec.
2. Surface mounted on FR4 board.
3. Pulse width limited by maximum junction temperature, $\text{Pw} \leq 10\mu\text{s}$, Duty cycle $\leq 2\%$.
4. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

CHARACTERISTICS CURVE

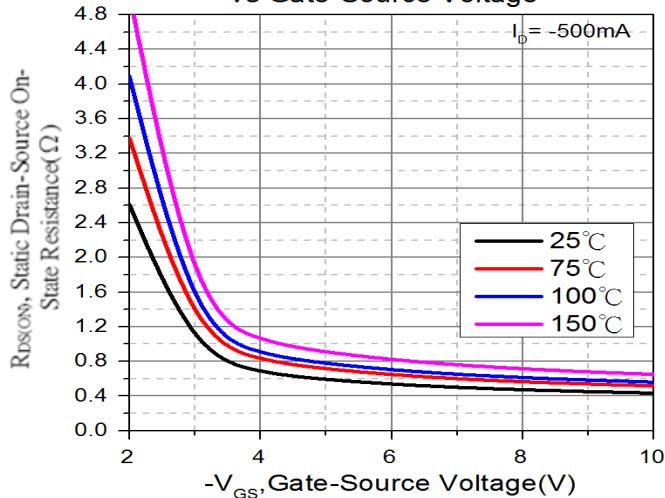
Typical Output Characteristics



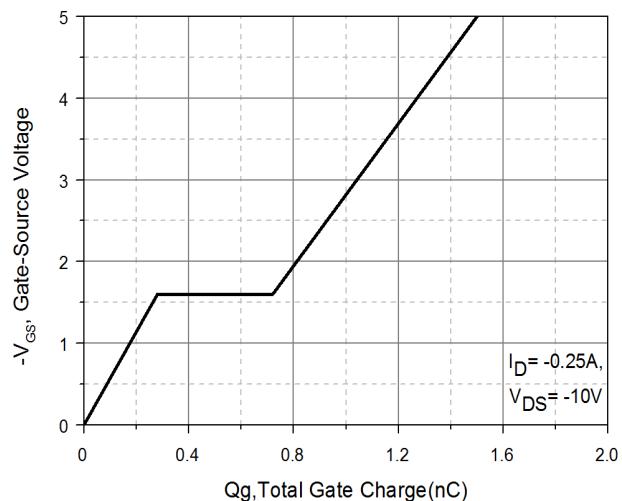
Reverse Drain Current vs Source-Drain Voltage



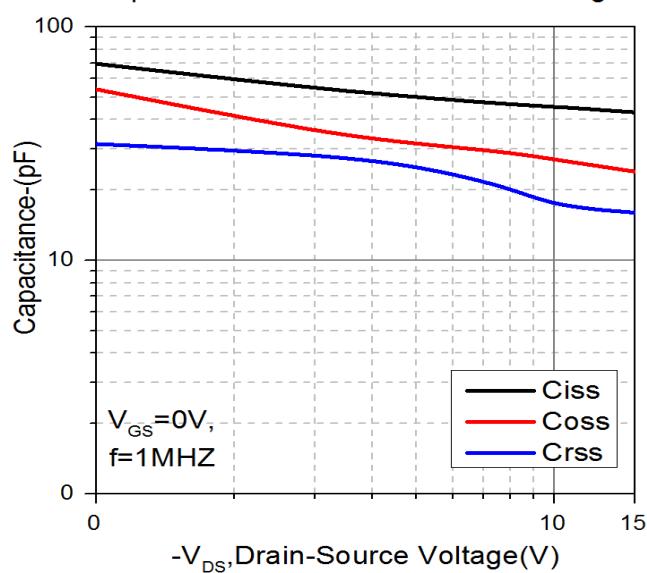
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Gate Charge Characteristics



Capacitance vs Drain-to-Source Voltage



Threshold Voltage vs Junction Temperature

